



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	10/03/2014
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	AMS/IPD Materials Declaration Champion)
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	ID07*01588I6	A	BO2A	10/03/2014
Amount	UoM	Unit type	ST ECOPACK Grade	
80.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.85X3.9X1.52	8	gull wing	
Comment	Package: SO 08 .15 JEDEC; MD valid for LM2904AYDT, LM158YDT, LM258AYDT, LM2904YDT, LM358YDT			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	IDO7*0158B16					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	0.718	mg	supplier	die	Silicon (Si)	7440-21-3		0.705	mg	981894	8813
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.006	mg	8357	75
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.003	mg	4178	38
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.004	mg	5571	50
Leadframe	Copper & its alloys	38.906	mg	supplier	alloy	Copper (Cu)	7440-50-8		38.808	mg	997481	485100
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.018	mg	463	225
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.033	mg	848	413
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.044	mg	1131	550
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.001	mg	26	13
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	26	13
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.001	mg	26	13
Die attach	Other Organic Materials	0.327	mg	supplier	glue	Silver (Ag)	7440-22-4		0.298	mg	911315	3725
Die attach				supplier	glue	acrylate	Proprietary		0.016	mg	48930	200
Die attach				supplier	glue	Methacrylate	Proprietary		0.013	mg	39755	163
Bonding wire	Other inorganic materials	0.054	mg	supplier	wire	Copper (Cu)	7440-50-8		0.054	mg	1000000	675
encapsulation	Other Organic Materials	39.995	mg	supplier	mold compound	Epoxy Resin	Proprietary		3	mg	75009	37500
encapsulation				supplier	mold compound	Phenol Resin	Proprietary		2	mg	50006	25000
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		34.635	mg	865983	432938
encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.2	mg	5001	2500
encapsulation				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.16	mg	4001	2000